■ 15-mA Constant-Current Outputs

For Driving Common-Anode LEDs such as TIL302 or TIL303 Without Series Resistors

Universal Logic Capabilities

Ripple Blanking of Extraneous Zeros Latch Outputs Can Drive Logic Processors Simultaneously

Decimal Point Driver Is Included

Synchronous BCD Counter Capability

Cascadable to N-Bits

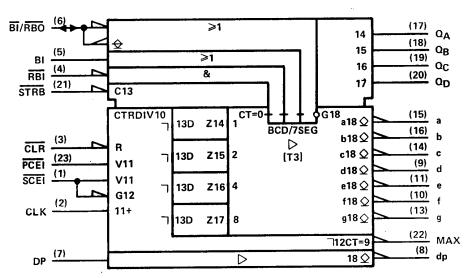
Look-Ahead-Enable Techniques Minimize Speed Degradation When Cascaded for Large-Word Display

Direct Clear Input

(TOP VIEW) SCEI 24 **Vcc** CLK 2 23 PECI CLR MAX 3 22 П STRB RBI 20□ ВΙ П5 QD BI/RBO QC DP QB 18[] QA dp d 16∏ b f а C е **GND** 13

N PACKAGE

logic symbol†



[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

description

This TTL MSI circuit contains the equivalent of 86 gates on a single chip. Logic inputs and outputs are completely TTL compatible. The buffered inputs are implemented with relatively large resistors in series with the bases of the input transistors to lower drive-current requirements to one-half of that required for a standard Series 54/74 TTL input. The serial-count-enable, actually two internal emitters, is rated as one standard Series 54/74 load. The logic outputs, except RBO, have active pull-ups.

The SN74143 driver output is designed specifically to maintain a relatively constant on-level sink current of approximately 15 milliamperes from output "a" through "g" and seven milliamperes from output "dp" over a voltage range from one to five volts. Any number of LED's in series may be driven as long as the output voltage rating is not exceeded.

All inputs are diode-clamped to minimize transmission-line effects, thereby simplifying system design. Maximum clock frequency is typically 18 megahertz and power dissipation is typically 280 milliwatts. The SN74143 is characterized for operation from 0°C to 70°C.



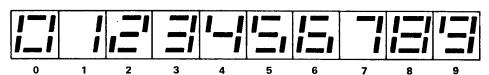
description (continued)

Functions of the inputs and outputs of these devices are as follows:

FUNCTION CLEAR INPUT	PIN NO. 3	DESCRIPTION When low, resets and holds counter at 0. Must be high for normal counting.
CLOCK INPUT	2	Each positive-going transition will increment the counter provided that the circuit is in the normal counting mode (serial and parallel count enable inputs low, clear input high).
PARALLEL COUNT ENABLE INPUT (PCEI)	23	Must be low for normal counting mode. When high, counter will be inhibited. Logic level must not be changed when the clock is low.
SERIAL COUNT ENABLE INPUT (SCEI)	1	Must be low for normal counting mode, also must be low to enable maximum count output to go low. When high, counter will be inhibited and maximum count output will be driven high. Logic level must not be changed when the clock is low.
MAXIMUM COUNT OUTPUT	22	Will go low when the counter is at 9 and serial count enable input is low. Will return high when the counter changes to 0 and will remain high during counts 1 through 8. Will remain high (inhibited) as long as serial count enable input is high.
LATCH STROBE INPUT	21	When low, data in latches follow the data in the counter. When high, the data in the latches are held constant, and the counter may be operated independently.
LATCH OUTPUTS (Q_A, Q_B, Q_C, Q_D)	17, 18, 19, 20	The BCD data that drives the decoder can be stored in the 4-bit latch and is available at these outputs for driving other logic and/or processors. The binary weights of the outputs are: $Q_A = 1$, $Q_B = 2$, $Q_C = 4$, $Q_D = 8$.
DECIMAL POINT INPUT	7	Must be high to display decimal point. The decimal point is not displayed when this input is low or when the display is blanked.
BLANKING INPUT (BI)	5	When high, will blank (turn off) the entire display and force $\overline{\text{RBO}}$ low. Must be low for normal display. May be pulsed to implement intensity control of the display.
RIPPLE-BLANKING INPUT (RBI)	4	When the data in the latches is BCD 0, a low input will blank the entire display and force the \overline{RBO} low. This input has no effect if the data in the latches is other than 0.
RIPPLE-BLANKING OUTPUT (RBO)	6	Supplies ripple blanking information for the ripple blanking input of the next decade. Provides a low if \overline{BI} is high, or if \overline{RBI} is low and the data in the latches in BCD 0; otherwise, this output is high. This pin has a resistive pull-up circuit suitable for performing a wire-AND function with any open-collector output. Whenever this pin is low the entire display will be blanked; therefore, this pin may be used as an active-low blanking input.
LED/LAMP DRIVER OUTPUTS (a, b, c, d, e, f, g, dp)	15, 16, 14, 9 11, 10, 13, 8	Outputs for driving seven-segment LED's or lamps and their decimal points. See segment identification and resultant displays on following page.

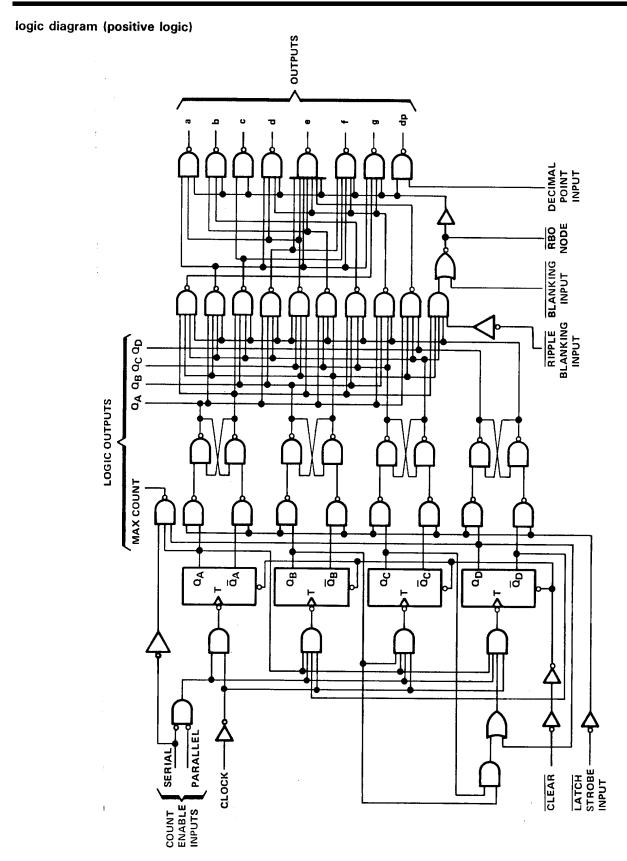






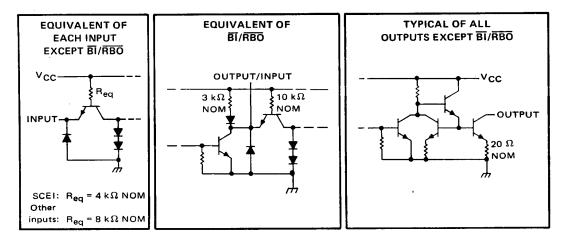
NUMERICAL DESIGNATIONS-RESULTANT DISPLAYS







schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)
Input voltage 5.5 V
Off-state current at outputs "a" thru "g" and "dp"
Continuous total power dissipation at (or below) 70°C free-air temperature (see Note 2) 1.4 W
Operating free-air temperature range 0°C to 70°C
Storage temperature range

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		MIN	NOM	MAX	UNIT	
Supply voltage, VCC	4.75	5	5.25	٧		
On-state voltage at outputs a thru g and d	1		5	٧		
High-level output current, IOH	QA, QB, QC, QD			- 240		
	Maximum count			- 560	μΑ	
	RBO			- 120		
Low-level output current, IOL	Q _A , Q _B , Q _C , Q _D , RBO			4.8	mA	
	Maximum count					
	High logic level	25			ns	
Clock pulse width, tw(clock)	Low logic level	55			115	
Clear pulse width, tw(clear)	25			ns		
	Serial and parallel carry	30†			ns	
Setup time, t _{SU}	Clear inactive state	60 [†]			115	
Operating free-air temperature, TA		0		70	°C	

 $^{^{\}dagger}$ The arrow indicates that the rising edge of the clock pulse is used for reference.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS†	MIN	TYP [‡]	MAX	UNIT	
VIH	High-level input voltage		2			V	
VIL	Low-level input voltage				0.8	V	
VIK	Input clamp voltage	$V_{CC} = MIN, I_{I} = -12 \text{ mA}$			- 1.5	V	
Vон	High-level output voltage I Ox Op Oc Op I		V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = MAX	2.4			V
VOL	LOW-level output voltage —	ow-level output voltage QA, QB, QC, RBO Maximum count				0.4	٧
V _{O(off)}	Off-state output voltage	Outputs a thru g, dp	$V_{CC} = MAX, I_{OH} = 250 \mu A$	7			V
V _{O(on)}	On-state output voltage	Outputs a thru g, dp	V _{CC} = MIN				V
I _{O(on)} On-state output current		Outputs a thru g	$V_{CC} = MIN, V_{O} = 1 V$ $V_{CC} = 5 V, V_{O} = 2 V$ $V_{CC} = MAX, V_{O} = 5 V$	9	15 15 15	22	mA
	·	Output dp	$V_{CC} = MIN, V_{O} = 1 V$ $V_{CC} = 5 V, V_{O} = 2 V$ $V_{CC} = MAX, V_{O} = 5 V$	4.5	7 7 7	12	
l _l	Input current at maximum input v	/oltage	$V_{CC} = MAX, V_1 = 5.5 V$			1	mA
I _{IH} High-level input current		Serial carry				40	μΑ
	High-level input current	RBO node	$V_{CC} = MAX, V_I = 2.4 V$	-0.12	-0.5		mA
	, i	Other inputs				20	μΑ
		Serial carry	.,			-1.6	
I _{IL} Low-level input cu	Low-level input current	RBO node	$V_{CC} = MAX, V_I = 0.4 V,$		- 1.5	-2.4	mA
		Other inputs	See Note 3			-0.8	
los	}	O _A , O _B , O _C , O _D	V _{CC} = MAX	-9 -15		- 27.5 - 55	mA
¹ CC	Supply current		V _{CC} = MAX, See Note 4		56	93	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

NOTES: 3. I_{IL} at $\overline{\text{RBO}}$ node is tested with $\overline{\text{BI}}$ grounded and RBI at 4.5 V.

- 4. ICC is measured after the following conditions are established:
 - a) Strobe = RBI = DP = 4.5 V
 - b) Parallel count enable = serial count enable = \overline{BI} = GND
 - c) Clear () then clock until all outputs are on ()
 - d) Outputs "a" through "g" and "dp" at 2.5 V, all other outputs open.

switching characteristics, VCC = 5 V, TA = 25 °C

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS			MAX	UNIT
f _{max}				12	18		MHz
tPLH		Maximum count	$C_L = 15 \text{ pF}, R_L = 560 \Omega,$ See Note 5		12	20	ns
tPHL	Serial look-ahead				23	35	
tPLH		Maximum count			26	40	
†PHL	Clock				29	45	ns
t _{PLH}	Clock	α _A , α _B , α _C , α _D	$C_L = 15 \text{ pF}, R_L = 1.2 \text{ k}\Omega,$		28	45	ns
^t PHL	O.O.O.K	-A/ -B/ -C/ -B					
				<u> </u>			<u> </u>



 $^{^{\}ddagger}$ All typical values are at VCC = 5 V, TA = 25 °C.

TYPICAL APPLICATION DATA

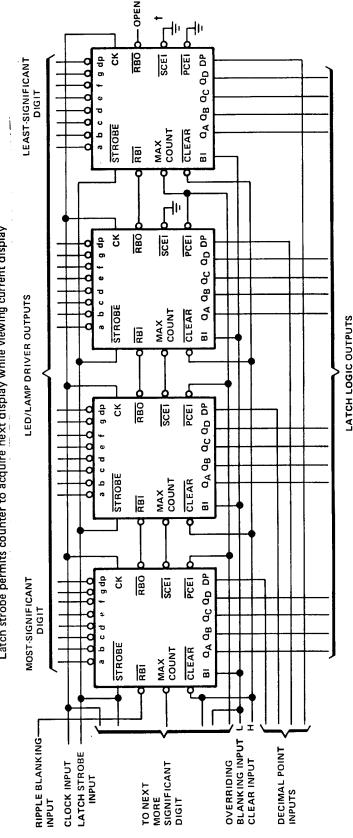
This application demonstrates how the drivers may be cascaded for N-bit display applications. It features:

Synchronous, look-ahead counting

Ripple blanking of leading zeros; blanking of trailing zeros (not illustrated) can also be implemented Overriding blanking for total suppression or intensity modulation of display

Direct parallel clear

Latch strobe permits counter to acquire next display while viewing current display







FUNCTION TABLE





The blanking input (BI) must be low when functions DECIMAL/0 through 20/RIPPLE BLANK are desired. RBI/RBÖ is wire-AND logic serving as ripple blanking input (RBI) and/or ripple blanking output (RBÖ). NOTES:

The ripple-blanking input (RBI) must be open or high to display a zero during the decimal 0 input.

When a high logic level is applied directly to the blanking input (81) all segment outputs are off regardless of any other input condition.

Condition: When the ripple-blanking input ($\overline{\mathsf{RBI}}$) and outputs Q_{A} through Q_{D} are at a low logic level, all segment outputs are off and the ripple-blanking output (RBO) goes to a low logic level (response condition).

SEGMENT IDENTIFICATION



PACKAGE OPTION ADDENDUM

11-Apr-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing		Qty	(2)		(3)		(4)	
SN74143N	OBSOLETE	PDIP	N	24		TBD	Call TI	Call TI	0 to 70		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

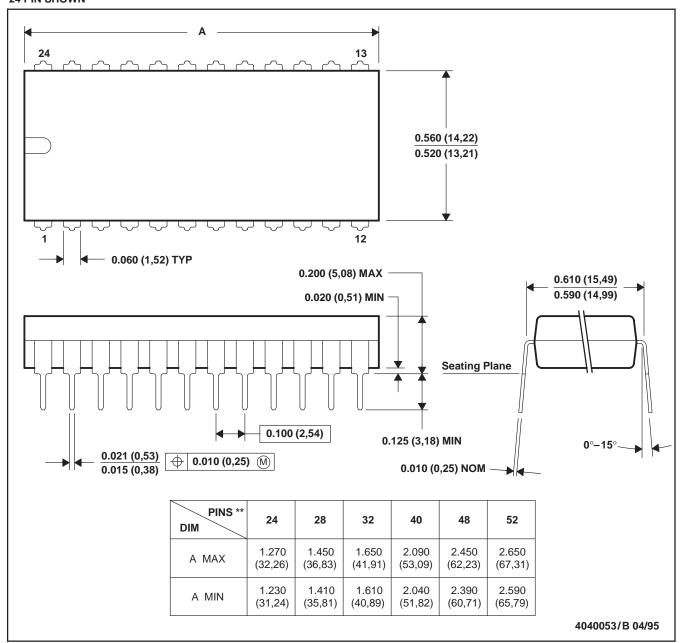
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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-011
- D. Falls within JEDEC MS-015 (32 pin only)



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